

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0736560001](#)  
**Status:** **Active**  
**Overview:** [hdm](#)  
**Description:** 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits

**Documents:**

[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

CSA LR19980  
 UL E29179

**General**

Product Family Backplane Connectors  
 Series [73656](#)  
 Application Backplane  
 Comments Midplane Power Module, Molex Series 73659  
 Component Type Power Header  
 Overview [hdm](#)  
 Product Name HDM®  
 Style N/A

**Physical**

Circuits (Loaded) 3  
 Circuits (maximum) 3  
 Color - Resin Black  
 Durability (mating cycles max) 250  
 First Mate / Last Break No  
 Flammability 94V-0  
 Guide to Mating Part No  
 Keying to Mating Part None  
 Material - Metal Beryllium Copper  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin-Lead  
 Material - Resin High Temperature Thermoplastic  
 Number of Columns 1  
 Number of Pairs Open Pin Field  
 Number of Rows 3  
 Orientation Vertical  
 PC Tail Length (in) 0.138 In  
 PC Tail Length (mm) 3.50 mm  
 PCB Locator No  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.098 In  
 PCB Thickness Recommended (mm) 2.50 mm  
 Packaging Type Tube  
 Pitch - Mating Interface (in) 0.000 In  
 Pitch - Mating Interface (mm) 0.00 mm  
 Plating min: Mating (µin) 30  
 Plating min: Mating (µm) 0.75  
 Plating min: Termination (µin) 35.2  
 Plating min: Termination (µm) 0.88  
 Polarized to PCB Yes  
 Stackable No

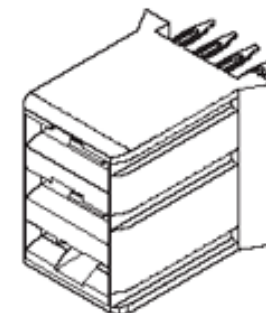


image - Reference only

Series

**EU RoHS**

**RoHS Compliant by Exemption**

**REACH SVHC**

**Contains SVHC: No**

**Halogen-Free**

**Status**

**Halogen-Free**

**China RoHS**



Pb

**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73656Series](#)

**Mates With**

[73651](#) HDM® Board-to-Board Daughterboard Power Module

**Application Tooling | FAQ**

*Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.*

**Global**

Description	Product #
Flat Rock Tooling for Pneumatic Press	<a href="#">0622013700</a>

Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

### **Electrical**

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	500V AC

### **Material Info**

### **Reference - Drawing Numbers**

Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999

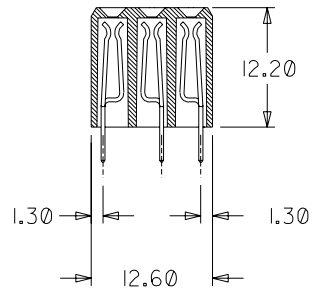
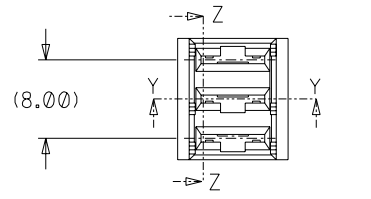
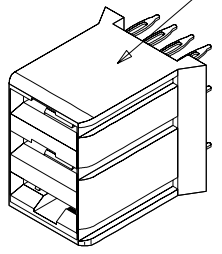
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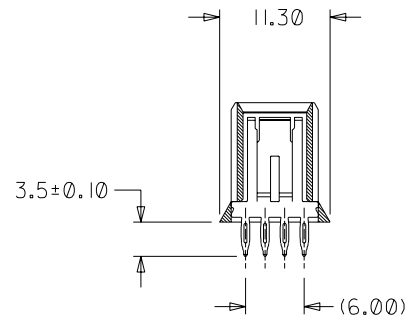
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ASSEMBLY NUMBER	FINISH
73656-0000	SEE NOTE 2.
73656-0001	SEE NOTE 3.

DATE CODE AND PART NUMBER ON THIS SURFACE OR SURFACE OPPOSITE.



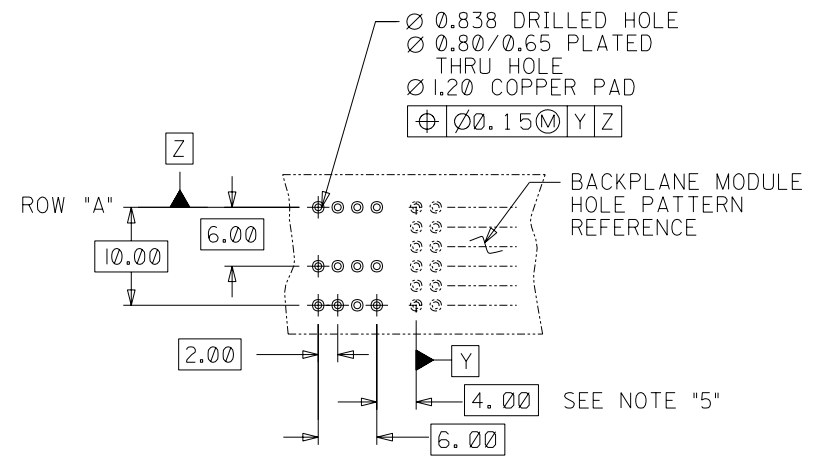
SECTION: Z-Z  
ROTATED 90° CW



SECTION: Y-Y

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK  
TERMINAL - COPPER ALLOY
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL
3. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; TIN / LEAD OVER NICKEL IN COMPLIANT AREA; NICKEL (Ni) OVERALL ON REMAINING WITH SEL. GOLD FLASH.
4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00mm.
5. DIMENSIONS ARE IN MILLIMETERS.
6. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
7. ASSEMBLIES PACKAGE PER PK-70873-0819.



PCB LAYOUT: COMPONENT SIDE  
RECOMMENDED PCB THICKNESS: 2.50 MIN

4	G
3	G
2	D
1	G
SH	REV.

G	ADD TOLERANCE PER UCP2004-1027 ELO 03/11/26	D	NEW MIDPLANE PER UDT2000-1298 ELO 00/06/20
F	ADD SHEET 4 PER UCP2003-0012 ELO 02/07/03	C	ADD TAIL LENGTH PER UDT2000-1240 ELO 00/06/08
E	ADD -5001 P/N PER UDT2002-0540 ELO 01/10/03	B	DATE CODE PER UDT2000-0399 ELO 99/10/26
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	± N/A
2 PLACE	± N/A
1 PLACE	± ---

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DRWG. BY: ELO	CHK'D. BY: SMR
APP'D. BY: CAB	SCALE: 2 : 1

REVISIONS		REVISE ONLY ON CAD SYSTEM	
TITLE: SALES ASSY, HDM BACKPLANE POWER MODULE (PRESS FIT)			
MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.		SHEET NO. 1 OF 4	DATE 98/05/21
PART NO. SDA-73656-*		DRWG. NO. *00*	
FILE NAME: S73656X1 DGN		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
DA	B	SIZE	